

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristic	Symbol	HD01	HD02	HD04	HD06	Unit
Peak Repetitive Reverse Voltage	V <sub>RMM</sub>					
Working Peak Reverse Voltage	V <sub>RWM</sub>	100	200	400	600	V
DC Blocking Voltage	V <sub>DC</sub>					
RMS Reverse Voltage	V <sub>RMS</sub>	70	140	280	420	V
Average Forward Rectified Current (Note 4) @T <sub>A</sub> = +40°C	I <sub>O</sub>	0.8				A
Non-Repetitive Peak Forward Surge Current, 8.3ms	I <sub>FSM</sub>	30				A
Single Half Sine-Wave Superimposed on Rated Load						

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Ambient (Note 4)	R <sub>θJA</sub>	75	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Instantaneous Voltage Drop @ 0.4A (Per Element)	V <sub>F</sub>	1.0	V
Peak Reverse Current at Rated @T <sub>A</sub> = +25°C	I <sub>R</sub>	5.0	μA
DC Blocking Voltage (Per Element) @T <sub>A</sub> = +125°C		500	
Typical Total Capacitance (Per Element) (Note 5)	C <sub>T</sub>	10	pF

Notes: 4. Mounted on PC Board.  
5. Measured at 1.0MHz and applied reverse voltage of 4.0V.

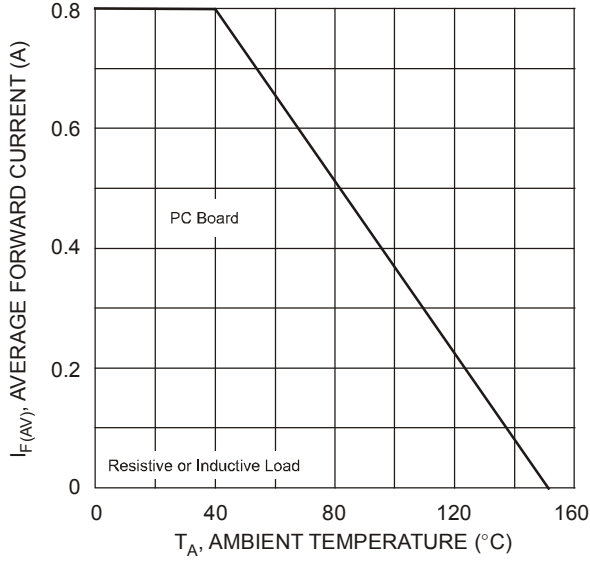


Fig. 1 Output Current Derating Curve

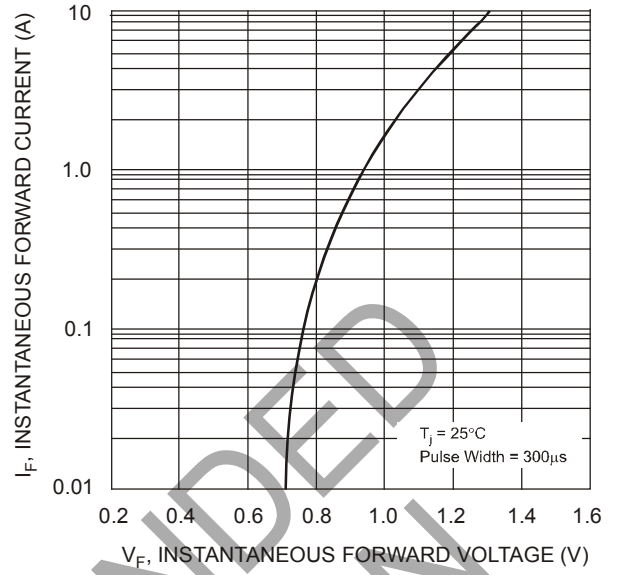


Fig. 2 Typical Forward Characteristics (per element)

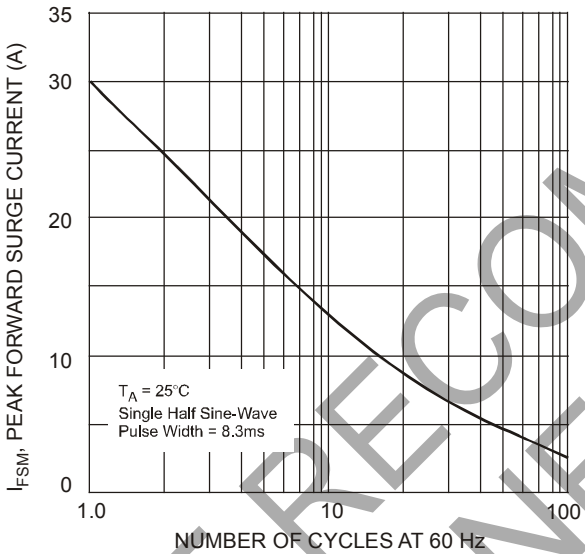


Fig. 3 Maximum Peak Forward Surge Current (per element)

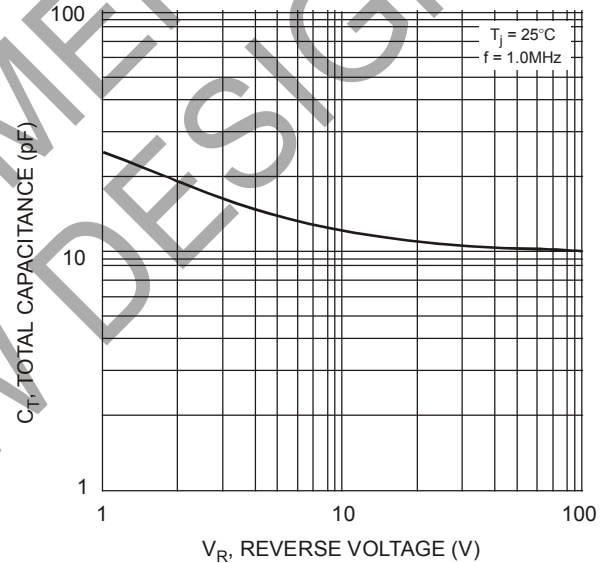


Fig. 4 Typical Total Capacitance (per element)

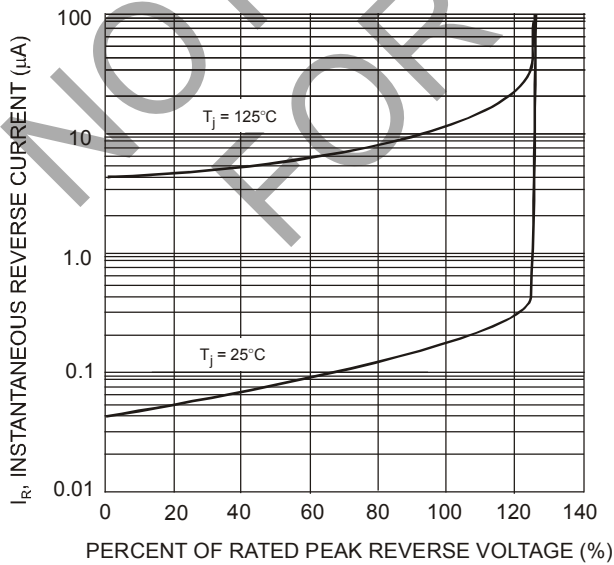
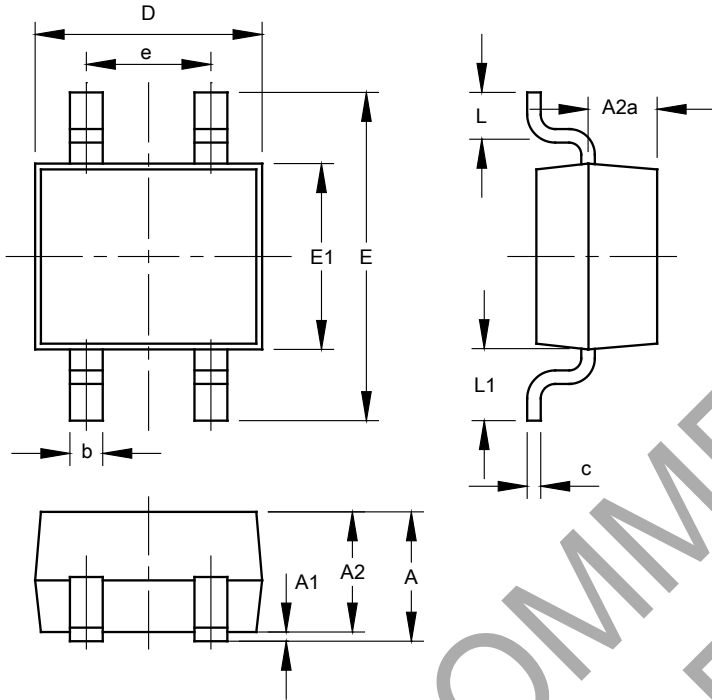


Fig. 5 Typical Reverse Characteristics (per element)

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**MiniDIP**

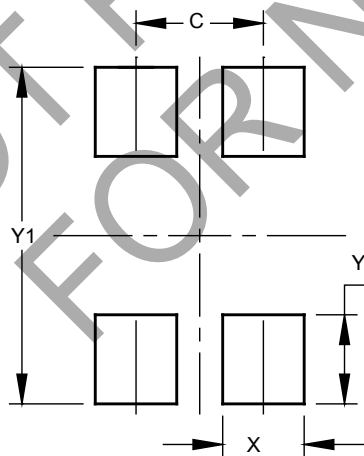


MiniDIP		
Dim	Min	Max
A	--	3.00
A1	--	0.20
A2	2.30	2.70
A2a	1.20	1.60
b	0.50	0.80
c	0.15	0.35
D	4.50	4.90
E	--	7.00
E1	3.60	4.00
e	2.30	2.70
L	0.70	1.10
L1	1.10	2.12
All Dimensions in mm		

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**MiniDIP**



Dimensions	Value (in mm)
C	2.50
X	1.65
Y	1.80
Y1	6.80

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